

Search Notes

Application/Control No.

10/688,954

Examiner

W. David Coleman

Applicant(s)/Patent under
Reexamination

KIM ET AL.

Art Unit

2823

SEARCHED

| Class | Subclass | Date | Examiner |
|-------|------------------|----------|----------|
| 438 | 14 441 687 | 3/2/2005 | WDC |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |
| | | | |

INTERFERENCE SEARCHED

| Class | Subclass | Date | Examiner |
|-------|----------|----------|----------|
| 438 | 14 | 3/2/2005 | WDC |
| | | | |
| | | | |
| | | | |

**SEARCH NOTES
(INCLUDING SEARCH STRATEGY)**

| | DATE | EXMR |
|---|----------|------|
| EAST 2.0.1; CAS STN; IEEE; Applicants claim a process of electrodeless copper deposition for analysis of defects on a wafer. | 3/2/2005 | WDC |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |
| | | |